

TECHNOMELT®

That's ME!

TECHNOMELT PUR ME

MICRO EMISSION PUR HOTMELT ADHESIVES FOR *FLAT LAMINATION*

- › Comprehensive product range
- › Covers all important application areas
- › All in proven and regularly monitored Micro Emission quality



Henkel

Henkel Adhesive Technologies

MICRO EMISSION PUR HOTMELT ADHESIVES FOR PROFILE WRAPPING

The lamination of panels with a wide range of substrates including wood, wood-derived materials, metals and plastics, is commonly known as “Flat Lamination”. Ideally suited for this application are polyurethane-based (PUR) adhesives. Our TECHNOMELT PUR Micro Emission products contain less than 0.1% diisocyanates.

They are free of hazard labels, and are exempt from the restrictions arising from REACH Annex 17. They therefore make a major contribution to occupational health and safety in the production of our customers.

Every PUR MicroEmission adhesive from Henkel is regularly tested for its diisocyanate content to ensure that it meets the legal requirement.

So that you can be sure to do the utmost for your staff. Promised!



TAILORED SOLUTIONS TO FULFILL YOUR NEEDS

Product	Basis	Viscosity, Brookfield mPas-s @ 130°C	Recommended working temperature		Characteristics
			in glue pot	on roller/nozzle	
TECHNOMELT PUR 4655 ME	PUR MicroEmission	10,000	130 – 150°C	130 – 150°C	Allrounder. High initial strength. Also suitable for materials with high spring back.
TECHNOMELT PUR 4663 ME	PUR MicroEmission	10,000	100 – 140°C	100 – 140°C	Allrounder
TECHNOMELT PUR 4671 ME	PUR MicroEmission	6,000 – 12,000	120 – 140°C	120 – 140°C	Very high initial strength. Very high heat resistance and cold flexibility. Excellent adhesion on many substrates (metals).
TECHNOMELT PUR 4688 ME	PUR MicroEmission	12,000	110 – 140°C	120 – 140°C	Allrounder. Universal applicable for all common substrates.

GET IN CONTACT WITH US

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